

ABSTRACT

5 An interconnect for testing semiconductor components
includes a substrate, and contacts on the substrate for
making temporary electrical connections with bumped contacts
on the components. Each contact includes a recess and a
pattern of leads cantilevered over the recess configured to
10 electrically engage a bumped contact. The leads are adapted
to move in a z-direction within the recess to accommodate
variations in the height and planarity of the bumped
contacts. In addition, the leads can include projections for
penetrating the bumped contacts, a non-bonding outer layer
15 for preventing bonding to the bumped contacts, and a curved
shape which matches a topography of the bumped contacts. The
leads can be formed by forming a patterned metal layer on the
substrate, by attaching a polymer substrate with the leads
thereon to the substrate, or by etching the substrate to form
20 conductive beams.

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